

What is claimed is:

~~1. A semiconductor device with a plurality of semiconductor chips stacked on a substrate, wherein said semiconductor device comprising;~~

5 a wiring layer disposed so as to be sandwiched between
said semiconductor chips, and

a plurality of bonding pads, for connecting a bonding wire, provided on said wiring layer, thereto.

2. A semiconductor device according to claim 1, wherein
10 a connection wiring for connecting among said bonding pads
is provided in said wiring layer.

3. A semiconductor device according to claim 1, wherein said plurality of bonding pads are disposed so as to surround a semiconductor chip stacked on an upper surface of said wiring layer.

4. A semiconductor device according to claim 1, wherein a via hole is provided in said wiring layer, said via hole is connected to a bonding pad of a semiconductor chip disposed below said wiring layer.

20 5. A semiconductor device with a plurality of
semiconductor chips stacked on a substrate, wherein said
semiconductor device comprising;

a wiring layer disposed so as to be sandwiched between
said semiconductor chips,

25 a plurality of bonding pads, for connecting a bonding
wire, provided on said wiring layer, thereto and

a connection wiring for connecting said bonding pads provided in said wiring layer.

6. A semiconductor device with a plurality of

a wiring layer disposed so as to be sandwiched between
said semiconductor chips,

a connection wiring for connecting among said bonding pads provided in said wiring layer, and

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